Product / Package Information

Package	LS6
Body Size	
Lead Count	
Terminal Finish	Au
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	N/A
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Ceramic Body

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Ceramics	Alumina	1344-28-1	4.58 E-02	89.23	892283	33.88	338810
Ceramics	Silicon Dioxide	14808-60-7	3.59 E-03	7.00	70024	2.66	26589
Ceramics	Zirconium Oxide	1314-23-4	7.97 E-04	1.55	15536	0.59	5899
Ceramics	Calcium Oxide	1305-78-8	6.95 E-04	1.36	13555	0.51	5147
Ceramics	Magnesium Oxide	1309-48-4	4.41 E-04	0.86	8602	0.33	3266
Subtotal			5.13 E-02	100.00	1000000	37.97	379711

Lid

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Ceramics	Alumina	1344-28-1	3.36 E-02	93.45	934460	24.85	248508
Ceramics	Inorganic Binders	Proprietary	1.60 E-03	4.47	44662	1.19	11877
Ceramics	Epoxy, B-Stage	7440-66-6	7.50 E-04	2.09	20878	0.56	5552
Subtotal			3.59 E-02	100.00	1000000	26.59	265938

Package Metal Base

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other non-ferrous metals and alloys	Molybdenum	1439-98-7	1.59 E-02	64.98	649812	11.77	117707
Copper & its alloys	Copper	1440-50-8	8.57 E-03	35.02	350188	6.34	63433
Subtotal			2.45 E-02	100.00	1000000	18.11	181140

Base Metal Brazing Alloy

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	1.79 E-03	79.12	791194	1.32	13219
Copper & its alloys	Copper	7440-50-8	4.71 E-04	20.88	208806	0.35	3489
Subtotal			2.26 E-03	100.00	1000000	1.67	16708

Package Metal Base Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.74 E-05	29.56	295585	0.04	425
Precious metals	Gold	7440-57-5	1.37 E-04	70.44	704415	0.10	1012
Subtotal			1.94 E-04	100.00	1000000	0.14	1437

Pad Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other non-ferrous metals and alloys	Tungsten	7440-33-7	8.35 E-03	81.09	810892	6.18	61821
Nickel & its alloys	Nickel	7440-02-0	5.95 E-04	5.78	57784	0.44	4405
Precious metals	Gold	7440-57-5	1.35 E-03	13.13	131324	1.00	10012
Subtotal			1.03 E-02	100.00	1000000	7.62	76238

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.67 E-04	99.99	1000000	0.20	1977

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	7.36 E-03	100.0	1000000	5.45	54460

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.03 E-03	70.00	672095	1.50	15048
Other organic materials	1,4 Bis(2,3-epoxypropoxy)butane	2425-79-8	3.96 E-04	20.00	130809	0.29	2929
Other organic materials	Diglycidylether of bisphenol-F	54208-63-8	3.96 E-04	7.50	130809	0.29	2929
Other organic materials	Aromatic Amine	Proprietary	2.00 E-04	1.50	66288	0.15	1484
Subtotal			3.02 E-03	99.0	1000000	2.24	22390

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.35 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary